

# LNJ216C8ARU

## Surface Mounting Chip LED

Microlens FD Type

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	60	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	100	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

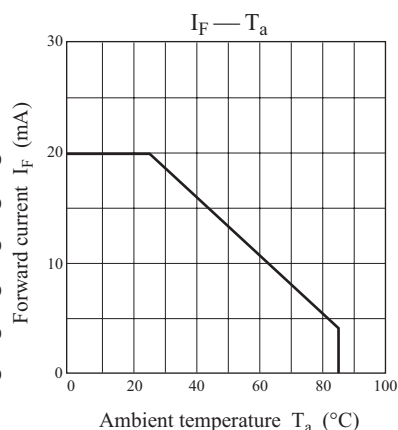
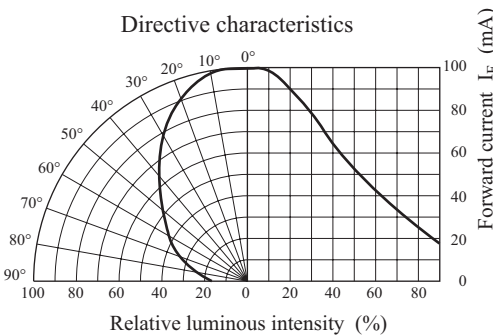
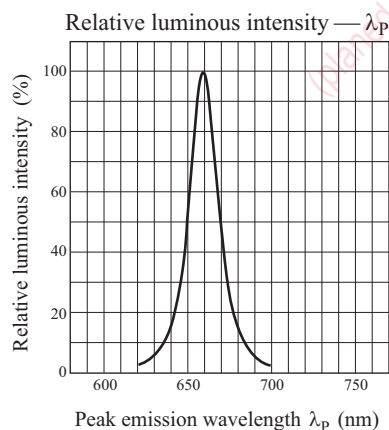
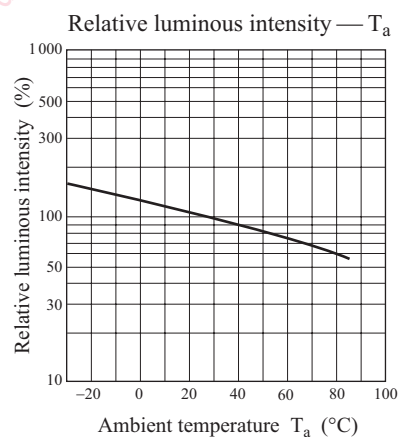
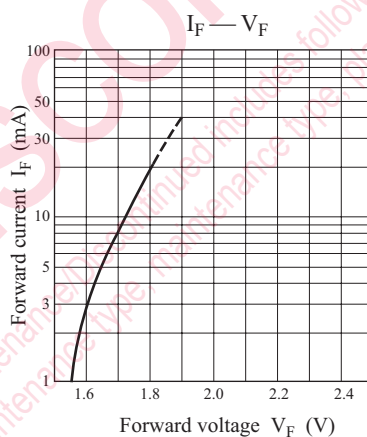
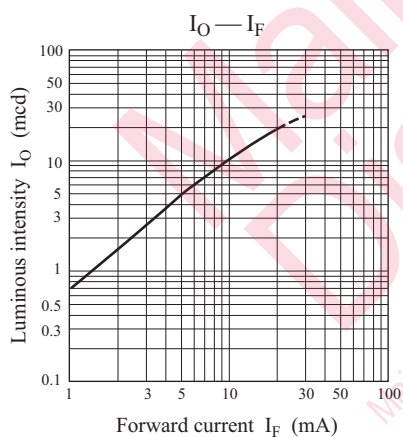
■ Lighting Color

- Red

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

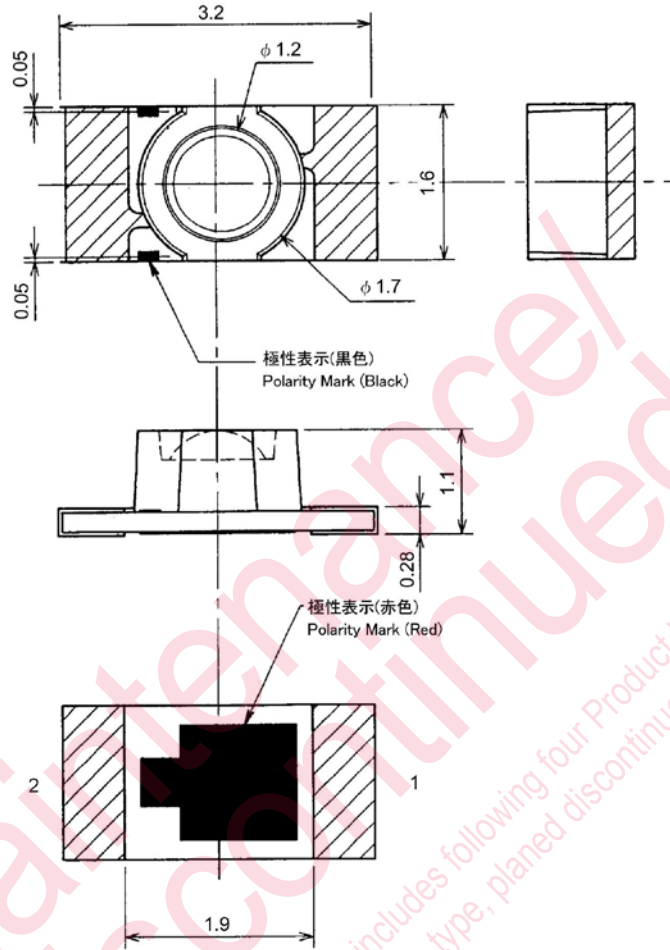
■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$	$I_F = 10\text{ mA}$	4.0	10.5		mcd
Reverse current	$I_R$	$V_R = 3\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		1.72	2.50	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		660		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		20		nm



■ Package (Unit: mm)

KLTLTN2K1600



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued includes following four Product lifecycle stage.  
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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